New SlurryScope™ Data Exposes Damaging Slurry Particles in Real Time

SEMICON West 2013
CAMPBELL, Calif.--(BUSINESS WIRE)--When Semicon West opens its three-day run on July 9th in San Francisco's Moscone Center, Vantage Technology will be participating both as a presenter in a joint paper with GlobalFoundries and as an exhibitor in the Malema Sensors booth (# 835). The company today confirmed that its presentation will disclose newly collected large particle count (LPC) data in undiluted CMP slurry, and how this data can be used to correlate slurry behavior with damaging wafer scratches. The SlurryScope systems collecting the data have been optimized for in-line detection of LPC as slurry moves between the sub-fab supply and the polishing tools in the fab.

"Real-time LPC detection is enabling new ways to improve slurry handling, minimize agglomeration and take preventive action to eliminate damaging wafer scratches," said Michael A. Fury, PhD, Vantage Director of Market Development. "When you consider how dramatically the number of potentially damaging particles increases at the 28nm node and below, it becomes important to continuously detect and classify LPC in production slurry." Since the introduction of the SlurryScope system in 2010, Vantage has shipped many production units and is still ramping up production to satisfy the demand for in-line monitoring of all slurry types being used in CMP systems at multiple fabs.

"SlurryScope metrology represents an invaluable real-time window into LPC behavior and the quality of production grade slurry being delivered to the CMP system platform," added Fury. "The shrinking critical dimensions of integrated circuits makes wafer scratching an increasingly serious defect component that can impact final production yield." He noted that the real-time data has catalyzed closer collaboration between process teams at major chip manufacturers with their sub-fab counterparts who are providing new slurry delivery systems and new slurry products.

Semicon West 2013 Presentation

During the "Lab-to-Fab: From R&D to High Volume Manufacturing" session at 3:10pm on Tuesday, July 9th, Carlo D. Aparece, Member of Technical Staff at GlobalFoundries (Fab 8), and Michael A. Fury, PhD, Vantage Director of Market Development, will present a paper titled "Real-time Large Particle Monitoring of CMP Slurries for Effective Management of Bulk Slurry Supply Systems."

About Vantage Technology
Headquartered in Campbell, California, Vantage Technology Corporation was founded in 2010 by Silicon Valley veterans with extensive experience in wafer fab production and test equipment. Focused on developing real-time micro-analytical metrology tools using advanced laser technology, proprietary algorithms and multicore image processing techniques, the company's initial product line targets the semiconductor industry. Vantage's SlurryScope™ systems continuously detect large particles in undiluted slurry in real time. For more information, visit www.VantageTechCorp.com.

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